

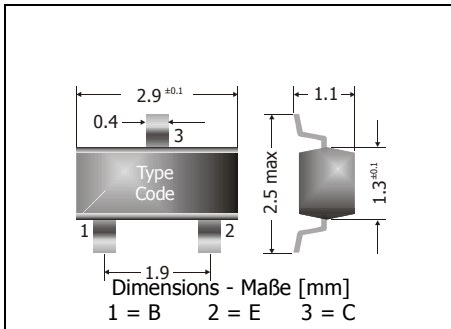
## BCW60A ... BCW60D

NPN

**Surface Mount General Purpose Si-Epi-Planar Transistors**  
**Si-Epi-Planar Universaltransistoren für die Oberflächenmontage**

NPN

Version 2006-07-31



Power dissipation – Verlustleistung

250 mW

Plastic case  
KunststoffgehäuseSOT-23  
(TO-236)

Weight approx. – Gewicht ca.

0.01 g

Plastic material has UL classification 94V-0  
Gehäusematerial UL94V-0 klassifiziertStandard packaging taped and reeled  
Standard Lieferform getupet auf RolleMaximum ratings ( $T_A = 25^\circ\text{C}$ )Grenzwerte ( $T_A = 25^\circ\text{C}$ )

			BCW60A ... BCW60D
Collector-Emitter-volt. – Kollektor-Emitter-Spannung	B open	$V_{CE0}$	32 V
Collector-Base-voltage – Kollektor-Basis-Spannung	E open	$V_{CB0}$	32 V
Collector-Base-voltage – Kollektor-Basis-Spannung	C open	$V_{EB0}$	5 V
Power dissipation – Verlustleistung		$P_{tot}$	250 mW <sup>1)</sup>
Collector current – Kollektorstrom (dc)		$I_C$	100 mA
Peak Collector current – Kollektor-Spitzenstrom		$I_{CM}$	200 mA
Peak Base current – Basis-Spitzenstrom		$I_{BM}$	200 mA
Junction temperature – Sperrschichttemperatur		$T_j$	-55...+150°C
Storage temperature – Lagerungstemperatur		$T_S$	-55...+150°C

Characteristics ( $T_j = 25^\circ\text{C}$ )Kennwerte ( $T_j = 25^\circ\text{C}$ )

			Min.	Typ.	Max.
DC current gain – Kollektor-Basis-Stromverhältnis <sup>2)</sup>					
$V_{CE} = 5\text{ V}, I_C = 10\ \mu\text{A}$	BCW60A	$h_{FE}$	20	140	–
	BCW60B	$h_{FE}$	20	200	–
	BCW60C	$h_{FE}$	40	300	–
	BCW60D	$h_{FE}$	100	460	–
$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	BCW60A	$h_{FE}$	120	170	220
	BCW60B	$h_{FE}$	180	250	310
	BCW60C	$h_{FE}$	250	350	460
	BCW60D	$h_{FE}$	380	500	630
$V_{CE} = 1\text{ V}, I_C = 50\text{ mA}$	BCW60A	$h_{FE}$	50	–	–
	BCW60B	$h_{FE}$	70	–	–
	BCW60C	$h_{FE}$	90	–	–
	BCW60D	$h_{FE}$	100	–	–

1 Mounted on P.C. board with 3 mm<sup>2</sup> copper pad at each terminal  
Montage auf Leiterplatte mit 3 mm<sup>2</sup> Kupferbelag (Lötpad) an jedem Anschluss

2 Tested with pulses  $t_p = 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$  – Gemessen mit Impulsen  $t_p = 300\ \mu\text{s}$ , Schaltverhältnis  $\leq 2\%$

Characteristics ( $T_j = 25^\circ\text{C}$ )Kennwerte ( $T_j = 25^\circ\text{C}$ )

	Min.	Typ.	Max.
Collector-Emitter saturation voltage – Kollektor-Sättigungsspannung <sup>2)</sup>			
$I_C = 10\text{ mA}, I_B = 0.25\text{ mA}$	–	120 mV	250 mV
$I_C = 50\text{ mA}, I_B = 1.25\text{ mA}$	–	200 mV	550 mV
Base-Emitter saturation voltage – Basis-Sättigungsspannung <sup>2)</sup>			
$I_C = 10\text{ mA}, I_B = 0.25\text{ mA}$	–	700 mV	850 mV
$I_C = 50\text{ mA}, I_B = 1.25\text{ mA}$	–	830 mV	1050 mV
Base-Emitter-voltage – Basis-Emitter-Spannung <sup>2)</sup>			
$I_C = 10\text{ }\mu\text{A}, V_{CE} = 5\text{ V}$	–	520 mV	–
$I_C = 2\text{ mA}, V_{CE} = 5\text{ V}$	550 mV	650 mV	750 mV
$I_C = 50\text{ mA}, V_{CE} = 1\text{ V}$	–	780 mV	–
Collector-Base cutoff current – Kollektor-Basis-Reststrom			
$V_{CB} = 30\text{ V}, (E\text{ open})$	–	–	20 nA
$V_{CE} = 30\text{ V}, T_j = 125^\circ\text{C}, (E\text{ open})$	–	–	20 $\mu\text{A}$
Emitter-Base cutoff current			
$V_{EB} = 4\text{ V}, (C\text{ open})$	–	–	20 nA
Gain-Bandwidth Product – Transitfrequenz			
$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}, f = 100\text{ MHz}$	$f_T$	100 MHz	250 MHz
Collector-Base Capacitance – Kollektor-Basis-Kapazität			
$V_{CB} = 10\text{ V}, I_E = i_e = 0, f = 1\text{ MHz}$	$C_{CBO}$	–	2 pF
Emitter-Base Capacitance – Emitter-Basis-Kapazität			
$V_{EB} = 10\text{ V}, I_C = i_c = 0, f = 1\text{ MHz}$	$C_{EBO}$	–	11 pF
Noise figure – Rauschzahl			
$V_{CE} = 5\text{ V}, I_C = 200\text{ }\mu\text{A}, R_G = 2\text{ k}\Omega$ $f = 1\text{ kHz}, \Delta f = 200\text{ Hz}$	F	–	2 dB
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft	$R_{thA}$	< 420 K/W <sup>1)</sup>	
Recommended complementary PNP transistors Empfohlene komplementäre PNP-Transistoren	BCW61A ... BCW61D		
Marking - Stempelung	BCW60A = AA BCW60B = AB BCW60C = AC BCW60D = AD		

<sup>2)</sup> Tested with pulses  $t_p = 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$  – Gemessen mit Impulsen  $t_p = 300\text{ }\mu\text{s}$ , Schaltverhältnis  $\leq 2\%$

<sup>1)</sup> Mounted on P.C. board with  $3\text{ mm}^2$  copper pad at each terminal  
Montage auf Leiterplatte mit  $3\text{ mm}^2$  Kupferbelag (Löt-pad) an jedem Anschluss